

**WHAT IS CLAIMED IS:**

1. A liquid crystal display device, comprising:  
a substrate;  
a UV hardening main sealant on the substrate;  
a UV hardening dummy sealant in a region between the UV hardening main sealant and an edge of the substrate; and  
a UV shielding part formed in a portion where the UV hardening dummy sealant is overlapped with a cell-cutting line.
2. The device of claim 1, wherein the UV shielding part is formed under the UV hardening dummy sealant.
3. The device of claim 1, wherein the UV shielding part is formed over the UV hardening dummy sealant.
4. The device of claim 1, wherein the UV shielding part is formed under and over the UV hardening dummy sealant.
5. The device of claim 1, wherein the UV shielding part is formed between the UV hardening dummy sealant and the substrate.
6. The device of claim 1, wherein the UV shielding part is formed at all intersections of the UV hardening dummy sealant and the cell-cutting line.

7. The device of claim 1, wherein the UV shielding part is formed at intersections of the UV hardening dummy sealant and the cell-cutting line at at least one side edge of the substrate.

8. The device of claim 1, wherein the UV shielding part is formed at intersections of the UV hardening dummy sealant and the cell-cutting line at opposite side edges of the substrate.

9. The device of claim 1, wherein the substrate includes a gate line, a data line, a thin film transistor and a pixel electrode.

10. The device of claim 9, wherein the UV shielding part is formed on the same layer as the gate line.

11. The device of claim 9, wherein the UV shielding part is formed on the same layer as the data line.

12. The device of claim 1, wherein the substrate includes a light-shielding layer, a color filter layer and a common electrode.

13. The device of claim 12, wherein the UV shielding part is formed on the same layer as the light-shielding layer.

14. The device of claim 1, further comprising a column spacer on the substrate.

15. A method for manufacturing an LCD device comprising:  
preparing first and second substrates;  
forming a UV shielding part in a dummy region on one of first and second substrates;  
forming a UV hardening main sealant on the substrate on which the UV shielding part is formed;  
forming a UV hardening dummy sealant on the substrate between the UV hardening main sealant and an edge of the substrate;  
applying a liquid crystal on one of the first and second substrates;  
attaching the first and second substrates;  
irradiating UV light onto the UV hardening main sealant and UV hardening dummy sealant; and  
cutting the substrates into unit cells.

16. The method of claim 15, further comprising:  
forming gate and data lines on the first substrate;  
forming a thin film transistor at a crossing point of the gate and data lines; and  
forming a pixel electrode on the first substrate.

17. The method of claim 16, wherein the UV shielding part is formed with the gate line.

18. The method of claim 16, wherein the UV shielding part is formed with the data line.

19. The method of claim 15, further comprising:

forming a light-shielding layer on the second substrate; and

forming a color filter layer on the light-shielding layer.

20. The method of claim 19, wherein the UV shielding part is formed with the light-shielding layer.

21. The method of claim 15, wherein the UV light is irradiated to the surface of the substrate on which the UV shielding part is formed.

22. The method of claim 15, further comprising heating the attached substrates after irradiating UV light to the attached substrates.

23. The method of claim 15, wherein cutting the substrates includes scribing and breaking processes in one step.

24. The method of claim 15, wherein irradiating UV light includes masking an active area inside the UV hardening main sealant.

25. The method of claim 15, wherein the UV hardening main and dummy sealants are formed on the second substrate, and the liquid crystal is dropped on the first substrate.

26. The method of claim 15, wherein the UV hardening main and dummy sealants are formed on the first substrate, and the liquid crystal is dropped on the second substrate.

27. The method of claim 15, further comprising a column spacer on one of the first and second substrates.

28. The method of claim 15, wherein the UV shielding part is formed in a portion where the UV hardening dummy sealant is overlapped with a cell-cutting line.